

IN THE CLAIMS

The following listing of the claims will replace all prior versions, and listings, of claims in the application:

Claims 1-12 (canceled).

13. (currently amended) A high density cable comprising:
an electrically conductive substrate;
a multi-layer interconnection circuit having conductive traces fabricated on said substrate and at least two attachment sites wherein each of said attachment sites includes a plurality of attachment terminals and each of said terminals connects with a selected trace of said interconnection circuit;
wherein at least one of said conductive traces is embedded in dielectric material in said multi-layer interconnection circuit so as to form a transmission line having a characteristic impedance.

14. (currently amended) The cable of Claim 13 wherein said attachment terminals are either ~~gold stud bumps~~ conductive bumps or wells filled with solder.

15. (canceled)

16. (canceled)

17. (original) The cable of Claim 13 wherein the pitch of said attachment terminals is 100 microns or less.

18. (currently amended) The cable of ~~Claims 13-17~~ Claim 13 and including multiple branches of said cable, wherein at least one of said attachment sites is provided in each of said branches.

Claims 19-35 (canceled).